

4096 BIT HIGH SPEED STATIC MOS RANDOM ACCESS MEMORY

3

DESCRIPTION

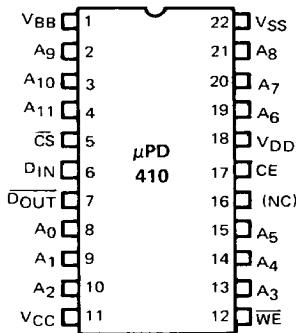
The μPD410 is a very high speed 4K bit static random access memory. It is organized as 4096 words by 1 bit per word and fabricated using N channel silicon gate MOS technology.

All signals to the device are TTL compatible except for Chip Enable which is standard +12 Volt MOS level.

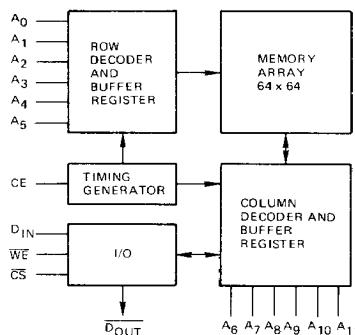
Circuit operation starts with the rising edge of CE. Data is latched and valid until falling edge of CE. Address and Chip Select signals are latched on-chip to simplify system timing requirements.

FEATURES

- 4096 Words x 1 Bit Organization
- Fully Decoded
- TTL Compatible (except CE)
- High Speed-Access Time: 90 ns max.
- Cycle Time: 220 ns min.
- Static Operation — No Refresh Required
- Standby Power: 75 mW max.
- Active Power: 470 mW typ.
- Supply Voltages: VDD = +12V, VCC = +5V, VBB = -5V
- Address Registers on the Chip
- Three State Output
- Standard 22 Pin Ceramic Dual-in-Line Package
- Pin Compatible with μPD411 and Other 4K Dynamic RAMs

PIN CONFIGURATION

μ PD410



BLOCK DIAGRAM

Operating Temperature	0°C to +70°C
Storage Temperature	-65°C to +150°C
All Output Voltages	-0.3 to +20 Volts ⁽¹⁾
All Input Voltages	-0.3 to +20 Volts ⁽¹⁾
Supply Voltage VDD	-0.3 to +20 Volts ⁽¹⁾
Supply Voltage VCC	-0.3 to +20 Volts ⁽¹⁾
Supply Voltage VSS	-0.3 to +20 Volts ⁽¹⁾
Power Dissipation	1.0W

Note: ⁽¹⁾ Relative to VBB

COMMENT: Stress above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

* $T_A = 25^\circ\text{C}$

$T_d = 0^\circ\text{C}$ to 70°C ; $V_{DD} = 12\text{V} \pm 5\%$; $V_{CC} = 5\text{V} \pm 5\%$; $V_{BB} = -5\text{V} \pm 5\%$; $V_{SS} = 0\text{V}$

PARAMETER	SYMBOL	LIMITS		UNIT	TEST CONDITIONS
		MIN	MAX		
Input Leakage Current	I _{LI}		10	μA	$V_{IN} = V_{ILMIN}$ to V_{IHMAX}
CE Input Leakage Current	I _{LC}		10	μA	$V_{IN} = V_{ILCMIN}$ to V_{IHCMAX}
Output Leakage Current	I _{LO}		10	μA	$CE = V_{ILC}$ or $CS = V_{IH}$ $V_O = 0\text{V}$ to 5.25V
V _{DD} Supply Current during CE off	I _{DDOFF}		200	μA	$CE = -1.0\text{V}$ to 0.6V
V _{DD} Supply Current during CE on	I _{DDON}		20	mA	$CE = V_{IHC}$
Average V _{DD} Current	μ PD410	I _{DDAV}	24	mA	Minimum Cycle Time
μ PD410-1	I _{DDAV}	32	mA		
μ PD410-2	I _{DDAV}	45	mA		
μ PD410-3	I _{DDAV}	45	mA		
V _{BB} Supply Current	I _{BB}		100	μA	
V _{CC} Supply Current during CE off	I _{CCOFF}		15	mA	$CE = V_{ILC}$ or $CS = V_{IH}$
Average V _{CC} Current	I _{CCAV}		21	mA	$DOUT = \text{No load}$
Input Low Voltage	V _{IL}	-1.0	0.6	V	
Input High Voltage	V _{IH}	2.4	$V_{CC} + 1$	V	
CE Input Low Voltage	V _{ILC}	-1.0	0.6	V	
CE Input High Voltage	V _{IHC}	$V_{DD} - 1$	$V_{DD} + 1$	V	
Output Low Voltage	V _{OL}	0	0.4	V	$I_{OL} = 3.2\text{ mA}$
Output High Voltage	V _{OH}	2.4	V _{CC}	V	$I_{OH} = 2.0\text{ mA}$

$T_A = 0^\circ\text{C}$ to 70°C ; $V_{DD} = 12\text{V} \pm 5\%$; $V_{CC} = 5\text{V} \pm 5\%$; $V_{BB} = -5\text{V} \pm 5\%$; $V_{SS} = 0\text{V}$

PARAMETER	SYMBOL	LIMITS			UNIT	TEST CONDITIONS
		MIN	TYP	MAX		
Address Capacitance	C _{AD}		4	6	pF	$V_{IN} = V_{SS}$
CS Capacitance	C _{CS}		4	6	pF	$V_{IN} = V_{SS}$
D _{IN} Capacitance	C _{DIN}		8	10	pF	$V_{IN} = V_{SS}$
D _{OUT} Capacitance	C _{OUT}		5	7	pF	$V_{OUT} = V_{SS}$
WE Capacitance	C _{WE}		8	10	pf	$V_{IN} = V_{SS}$
CE Capacitance	C _{CE}		18	27	pf	$V_{IN} = V_{SS}$

ABSOLUTE MAXIMUM RATINGS*

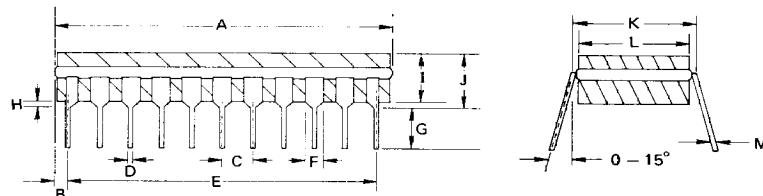
DC CHARACTERISTICS

CAPACITANCE

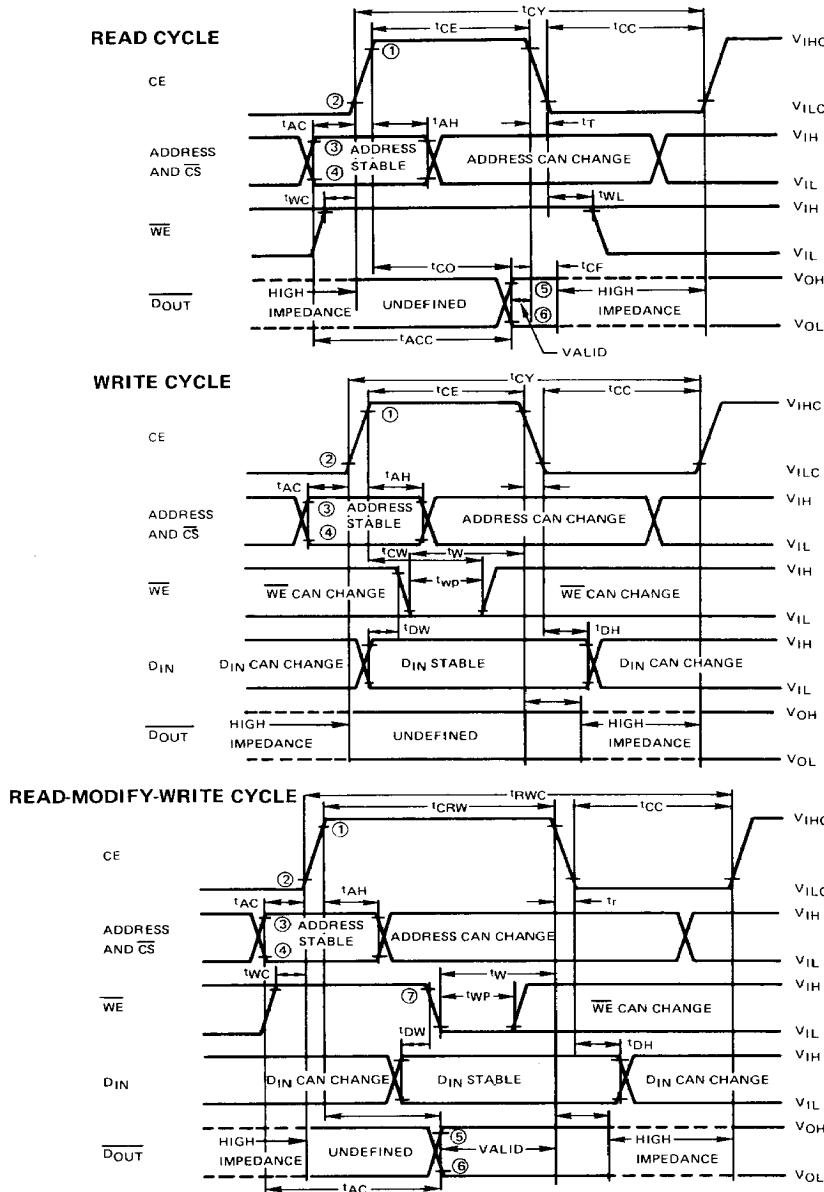
AC CHARACTERISTICS

 $T_a = 0^\circ C \text{ to } 70^\circ C; V_{DD} = 12V \pm 5\%; V_{CC} = 5V \pm 5\%; V_{BB} = -5V \pm 5\%; V_{SS} = 0V$

PARAMETER	SYMBOL	LIMITS								UNIT	TEST CONDITIONS
		410		410-1		410-2		410-3			
MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
READ, WRITE AND READ-MODIFY-WRITE											
Address to CE Set Up Time	t _{AC}	0		0		0		0		ns	
Address Hold Time	t _{AH}	90		70		50		50		ns	
CE Off Time	t _{CC}	190		140		90		90		ns	
CE Transition Time	t _T	0	40	0	40	0	40	0	40	ns	
CE off to Output High Impedance State	t _{CF}	0	90	0	90	0	90	0	90	ns	
READ											
Cycle Time	t _{CY}	440		330		220		220		ns	t _T = 10 ns
CE on Time	t _{CE}	230	2000	170	2000	110	2000	110	2000	ns	
CE Output Delay	t _{CO}		190		140		90		80	ns	Load = 50 pF + TTL, Ref = 2.0 or 0.8V
Access Time	t _{ACC}		200		150		100		90	ns	t _{ACC} = t _{AC} + t _{CO} + t _T
CE to WE	t _{WL}	20		20		20		20		ns	
WE to CE on	t _{WC}	0		0		0		0		ns	
WRITE											
Cycle Time	t _{CY}	440		330		220		220		ns	t _T = 10 ns
CE on Time	t _{CE}	230	2000	170	2000	110	2000	110	2000	ns	
WE to CE off	t _W	130		100		70		70		ns	
CE to WE	t _{CW}	130		100		70		70		ns	
DIN to WE Set Up	t _{DW}	0		0		0		0		ns	
DIN Hold Time	t _{DH}	60		40		20		20		ns	
WE Pulse Width	t _{WP}	130		100		70		70		ns	
DIN to WE Set Up	t _{DW}	0		0		0		0		ns	
DIN Hold Time	t _{DH}	60		40		20		20		ns	
CE to Output Delay	t _{CO}		190		140		90		80	ns	Load = 50 pF + TTL, Ref = 2.0 or 0.8V
Access Time	t _{ACC}		200		150		100		90	ns	t _{ACC} = t _{AC} + t _{CO} + t _T
READ-MODIFY-WRITE											
Read-Modify-Write (RMW) Cycle Time	t _{RWC}	560		420		280		280		ns	t _T = 10 ns
CE Width During RMW	t _{CRW}	350	2000	260	2000	170	2000	170	2000	ns	
WE to CE on	t _{WC}	0		0		0		0		ns	
WE to CE off	t _W	130		100		70		70		ns	
WE Pulse Width	t _{WP}	130		100		70		70		ns	
DIN to WE Set Up	t _{DW}	0		0		0		0		ns	
DIN Hold Time	t _{DH}	60		40		20		20		ns	
CE to Output Delay	t _{CO}		190		140		90		80	ns	Load = 50 pF + TTL, Ref = 2.0 or 0.8V
Access Time	t _{ACC}		200		150		100		90	ns	t _{ACC} = t _{AC} + t _{CO} + t _T

PACKAGE OUTLINE
μPD410D

ITEM	MILLIMETERS	INCHES
A	27.43 Max.	1.079 Max.
B	1.27 Max.	0.05 Max.
C	2.54 ± 0.1	0.10
D	0.42 ± 0.1	0.016
E	25.4 ± 0.3	1.0
F	1.5 ± 0.2	0.059
G	3.5 ± 0.3	0.138
H	3.7 ± 0.3	0.145
I	4.2 Max.	0.165 Max.
J	5.08 Max.	0.200 Max.
K	10.16 ± 0.15	0.400
L	9.1 ± 0.2	0.358
M	0.25 ± 0.05	0.009



- Notes:
- ① $V_{DD} - 2V$ is the reference level for measuring timing of CE.
 - ② $V_{SS} + 2V$ is the reference level for measuring timing of CE.
 - ③ V_{IHM} is the reference level for measuring timing of the addresses, CS, WE and DIN.
 - ④ V_{ILM} is the reference level for measuring timing of the addresses, CS, WE and DIN.
 - ⑤ $V_{SS} + 2.0V$ is the reference level for measuring timing of \bar{D}_{OUT} .
 - ⑥ $V_{SS} + 0.8V$ is the reference level for measuring timing of \bar{D}_{OUT} .
 - ⑦ WE must be at V_{IH} until end of t_{CO} .

The information presented in this document is believed to be accurate and reliable. The information is subject to change without notice.
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